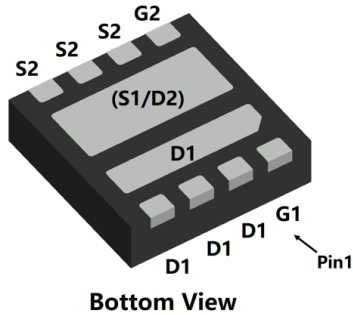
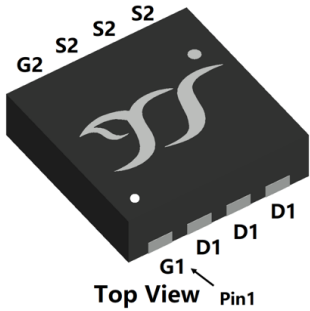
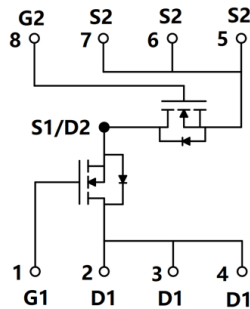


N-Channel and N-Channel Complementary MOSFET



DFN3030-8L



Product Summary NMOS(Die1)

- V_{DS} 30V
- I_D 30A
- $R_{DS(ON)}$ (at $V_{GS}=10V$) $< 10m\Omega$
- $R_{DS(ON)}$ (at $V_{GS}=4.5V$) $< 19.5m\Omega$

NMOS(Die2)

- V_{DS} 30V
- I_D 40A
- $R_{DS(ON)}$ (at $V_{GS}=10V$) $< 6.5m\Omega$
- $R_{DS(ON)}$ (at $V_{GS}=4.5V$) $< 15m\Omega$

General Description

- Dual Asymmetric N-Channel
- High Current Capability
- Low Gate Charge
- Epoxy Meets UL 94 V-0 Flammability Rating
- Halogen Free

Applications

- DC/DC Converters in Computing, Servers
- Isolated DC/DC Converters in Telecom and Industrial

■ Absolute Maximum Ratings ($T_A=25^\circ C$ unless otherwise noted)

Parameter		Symbol	NMOS(Die1)	NMOS(Die2)	Unit
Drain-source Voltage		V_{DS}	30	30	V
Gate-source Voltage		V_{GS}	± 20	± 20	V
Drain Current	$T_A=25^\circ C$	I_D	9	11	A
	$T_A=100^\circ C$		5	7	
	$T_C=25^\circ C$		30	40	
	$T_C=100^\circ C$		19	25	
Pulsed Drain Current ^A		I_{DM}	120	160	A
Avalanche energy ^B		EAS	42.2	60	mJ
Total Power Dissipation ^C	$T_A=25^\circ C$	P_D	1.56	1.66	W
	$T_A=100^\circ C$		0.62	0.66	
	$T_C=25^\circ C$		17.3	20.8	
	$T_C=100^\circ C$		6.9	8.3	
Junction and Storage Temperature Range		T_J, T_{STG}	-55~+150	-55~+150	$^\circ C$

■ Thermal resistance

Parameter		Symbol	NMOS(Die1)		NMOS(Die2)		Units
			Typ	Max	Typ	Max	
Thermal Resistance Junction-to-Ambient ^D	Steady-State	$R_{\theta JA}$	67	80	62	75	$^\circ C/W$
Thermal Resistance Junction-to-Case	Steady-State	$R_{\theta JC}$	6	7.2	5	6	

■ Ordering Information (Example)

PREFERRED P/N	PACKING CODE	Marking	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
YJQD3622A	F1	QD3622A	5000	10000	100000	13" reel



YJQD3622A

■ NMOS(Die1) Electrical Characteristics (T_J=25°C unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Static Parameter						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} = 0V, I _D =250μA	30	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =30V, V _{GS} =0V	-	-	1	μA
		V _{DS} =30V, V _{GS} =0V, T _J =150°C	-	-	100	
Gate-Body Leakage Current	I _{GSS}	V _{GS} = ±20V, V _{DS} =0V	-	-	±100	nA
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D =250μA	1.1	1.5	2.2	V
Static Drain-Source On-Resistance	R _{DS(on)}	V _{GS} =10V, I _D =13A	-	7.5	10	mΩ
		V _{GS} =4.5V, I _D =10A	-	14	19.5	
Diode Forward Voltage	V _{SD}	I _S =10A, V _{GS} =0V	-	-	1.2	V
Gate resistance	R _G	f=1MHz	-	3	-	Ω
Maximum Body-Diode Continuous Current	I _S		-	-	30	A
Dynamic Parameters						
Input Capacitance	C _{iss}	V _{DS} =15V, V _{GS} =0V, f=1MHz	-	1020	-	pF
Output Capacitance	C _{oss}		-	140	-	
Reverse Transfer Capacitance	C _{rss}		-	125	-	
Switching Parameters						
Total Gate Charge	Q _g	V _{GS} =10V, V _{DS} =15V, I _D =13A	-	20.7	-	nC
Gate-Source Charge	Q _{gs}		-	3.8	-	
Gate-Drain Charge	Q _{gd}		-	5.3	-	
Reverse Recovery Charge	Q _{rr}	I _F =13A, di/dt=100A/us	-	161	-	nC
Reverse Recovery Time	t _{rr}		-	136	-	ns
Turn-on Delay Time	t _{D(on)}	V _{GS} =10V, V _{DD} =15V, I _D =13A R _{GEN} =2.2Ω	-	8.2	-	ns
Turn-on Rise Time	t _r		-	53.9	-	
Turn-off Delay Time	t _{D(off)}		-	18.4	-	
Turn-off fall Time	t _f		-	2.9	-	



YJQD3622A

■ NMOS(Die2) Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Static Parameter						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	30	-	-	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=30V, V_{GS}=0V$	-	-	1	μA
		$V_{DS}=30V, V_{GS}=0V, T_J=150^\circ\text{C}$	-	-	100	
Gate-Body Leakage Current	I_{GSS}	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	± 100	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	1.1	1.5	2.2	V
Static Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=10V, I_D=15A$	-	5	6.5	m Ω
		$V_{GS}=4.5V, I_D=10A$	-	11	15	
Diode Forward Voltage	V_{SD}	$I_S=10A, V_{GS}=0V$	-	-	1.2	V
Gate resistance	R_G	$f=1\text{MHz}$	-	3	-	Ω
Maximum Body-Diode Continuous Current	I_S		-	-	40	A
Dynamic Parameters						
Input Capacitance	C_{iss}	$V_{DS}=15V, V_{GS}=0V, f=1\text{MHz}$	-	1320	-	pF
Output Capacitance	C_{oss}		-	185	-	
Reverse Transfer Capacitance	C_{rss}		-	170	-	
Switching Parameters						
Total Gate Charge	Q_g	$V_{GS}=10V, V_{DS}=15V, I_D=15A$	-	27	-	nC
Gate-Source Charge	Q_{gs}		-	5	-	
Gate-Drain Charge	Q_{gd}		-	7	-	
Reverse Recovery Charge	Q_{rr}	$I_F=15A, di/dt=100A/\mu s$	-	157	-	nC
Reverse Recovery Time	t_{rr}		-	130	-	ns
Turn-on Delay Time	$t_{D(on)}$	$V_{GS}=10V, V_{DD}=15V, I_D=15A$ $R_{GEN}=2.2\Omega$	-	10.8	-	ns
Turn-on Rise Time	t_r		-	64.8	-	
Turn-off Delay Time	$t_{D(off)}$		-	22.5	-	
Turn-off fall Time	t_f		-	3.7	-	

A. Repetitive rating; pulse width limited by max. junction temperature.

B. NMOS(Die1): $T_J=25^\circ\text{C}$, $V_G=10V$, $R_G=25\Omega$, $L=0.5\text{mH}$, $I_{AS}=13A$.
NMOS(Die2): $T_J=25^\circ\text{C}$, $V_G=10V$, $R_G=25\Omega$, $L=0.5\text{mH}$, $I_{AS}=15.5A$.

C. P_d is based on max. junction temperature, using junction-case and junction-ambient thermal resistance.

D. The value of $R_{\theta JA}$ is measured with the device mounted on 1 in² FR-4 board with 2oz. Copper, in the still air environment with $T_A=25^\circ\text{C}$.
The maximum allowed junction temperature of 150°C . The value in any given application depends on the user's specific board design.



■ NMOS(Die1) Typical Electrical and Thermal Characteristics Diagrams

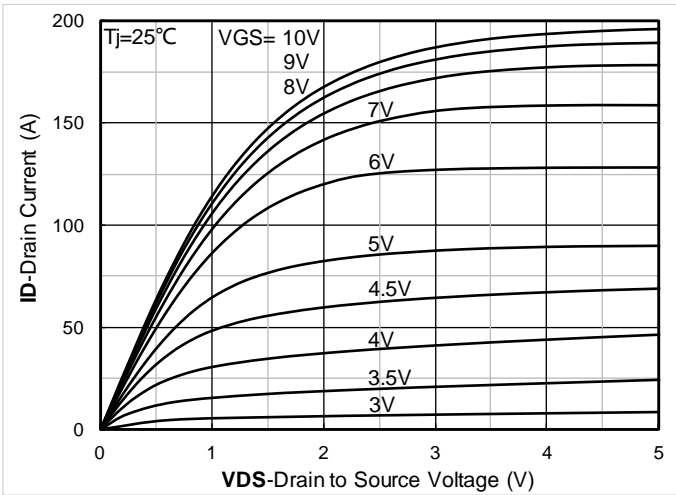


Figure 1. Output Characteristics

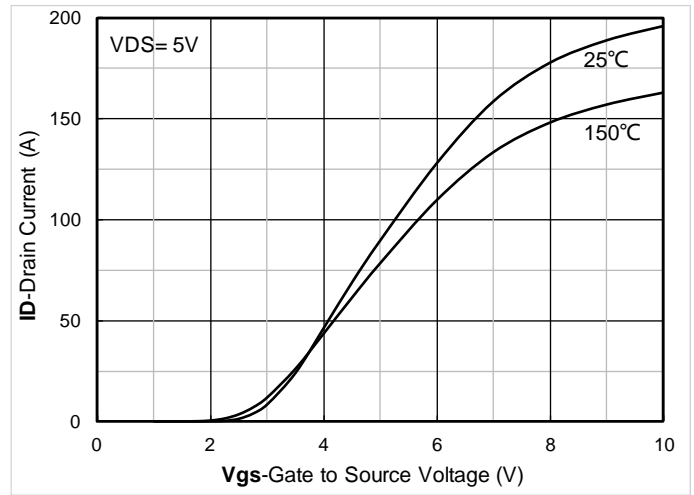


Figure 2. Transfer Characteristics

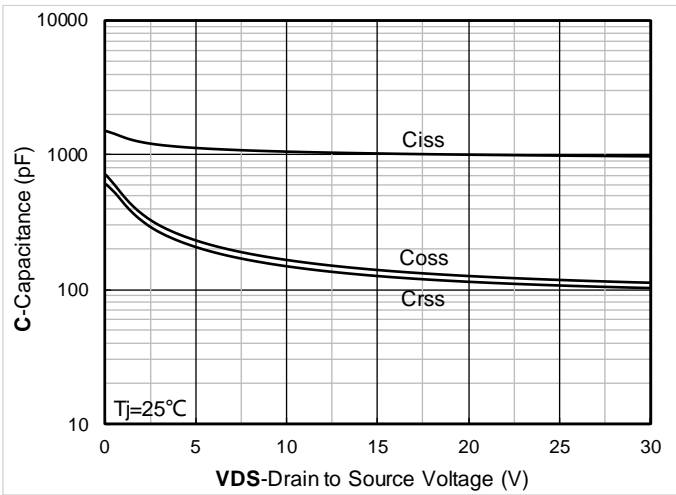


Figure 3. Capacitance Characteristics

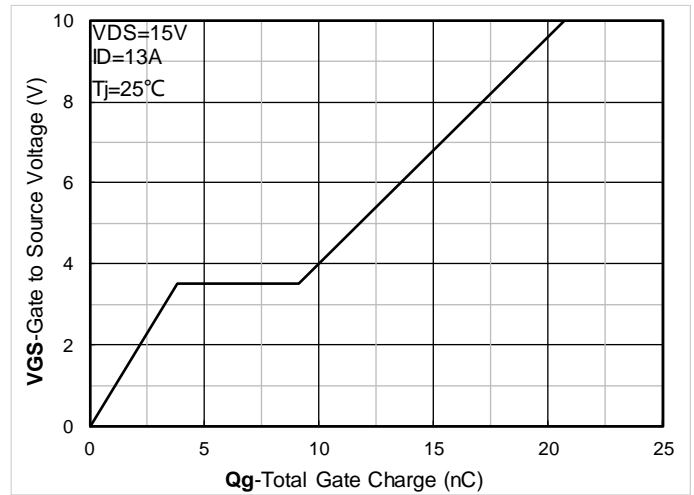


Figure 4. Gate Charge

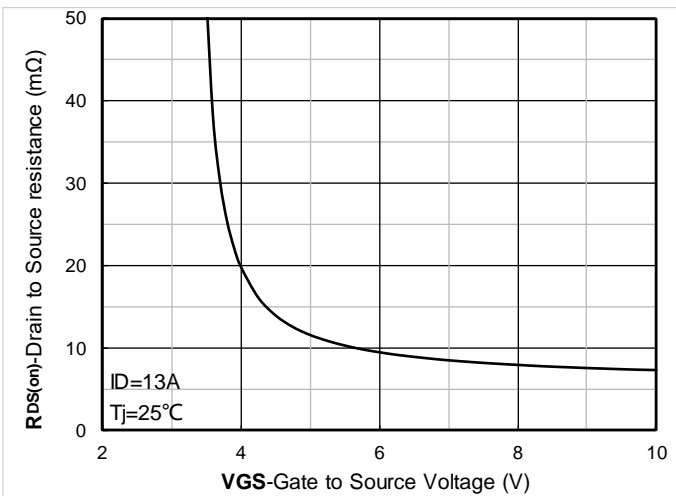


Figure 5. On-Resistance vs Gate to Source Voltage

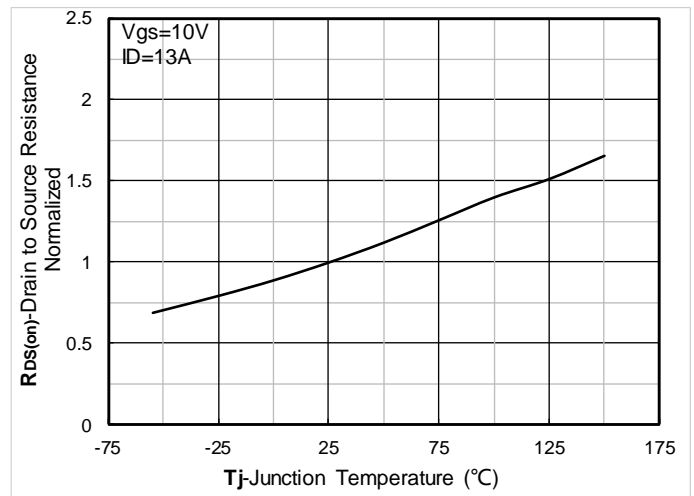


Figure 6. Normalized On-Resistan



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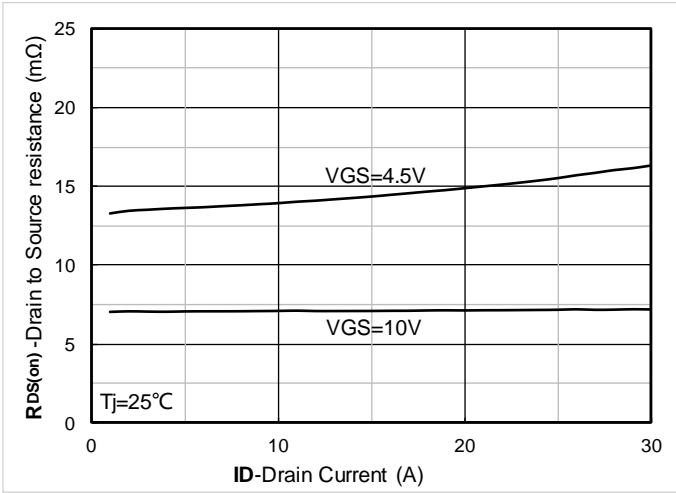


Figure 7. $R_{DS(on)}$ VS Drain Current

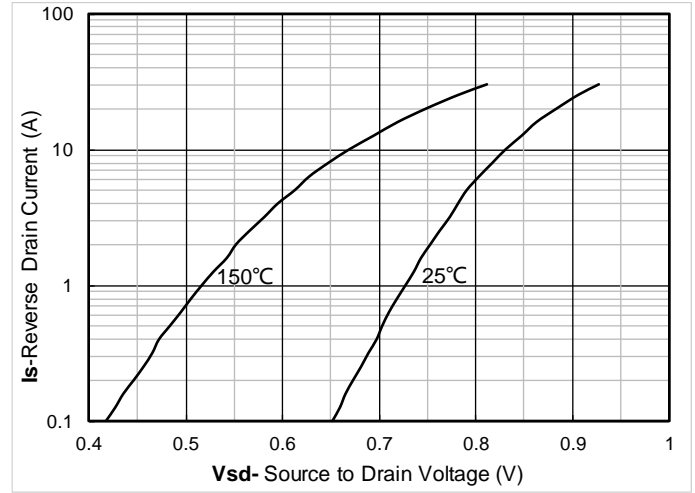


Figure 8. Forward characteristics of reverse diode

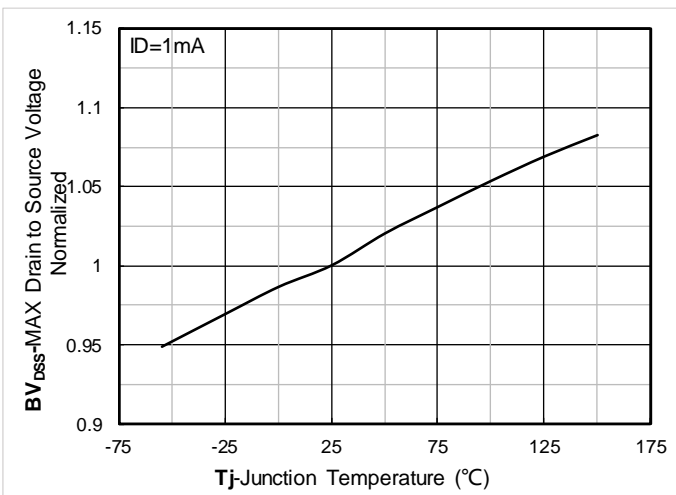


Figure 9. Normalized breakdown voltage

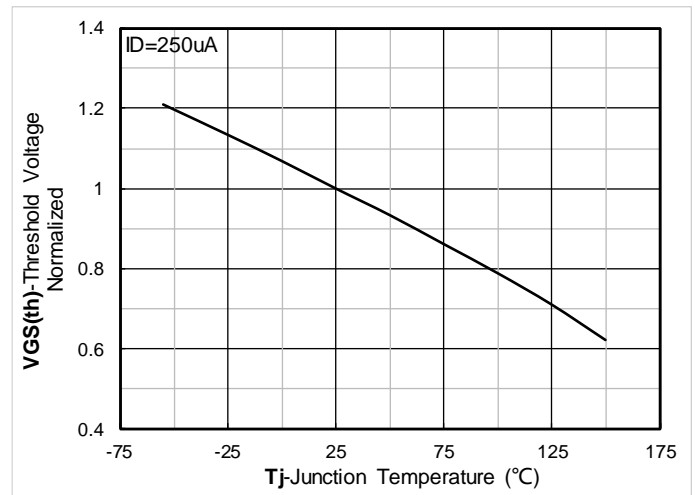


Figure 10. Normalized Threshold voltage

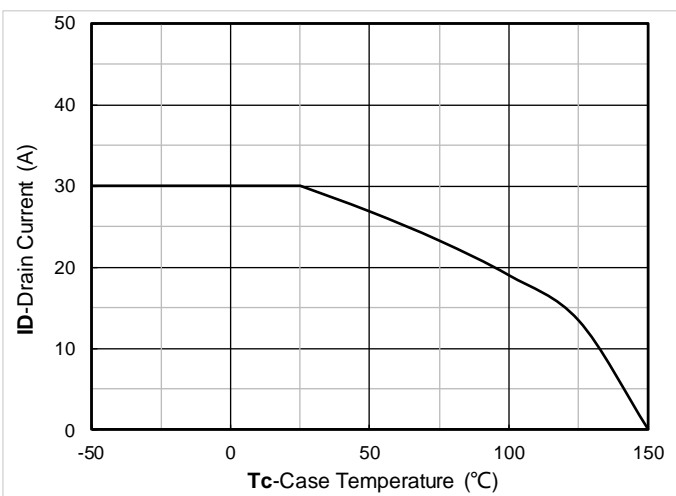


Figure 11. Current dissipation

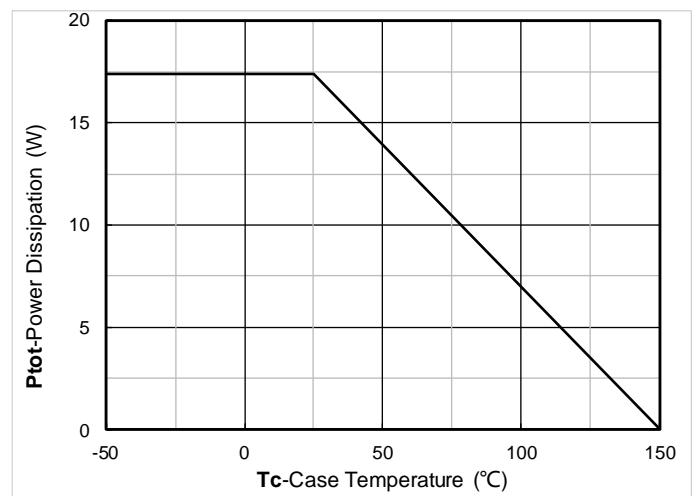


Figure 12. Power dissipation

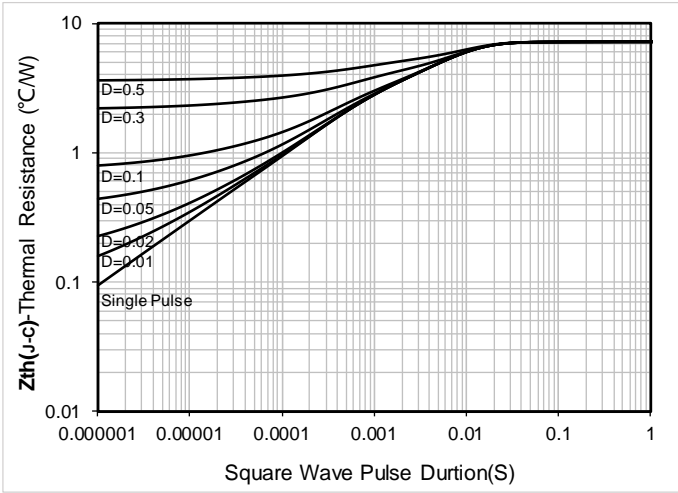


Figure 13. Maximum Transient Thermal Impedance

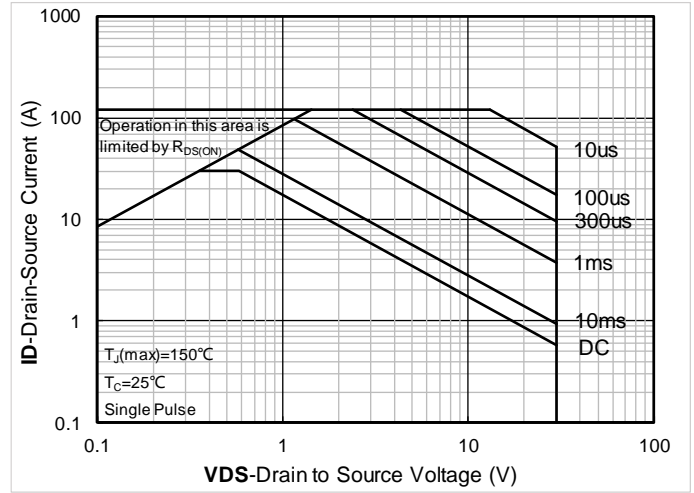


Figure 14. Safe Operation Area

■ NMOS(Die2) Typical Electrical and Thermal Characteristics Diagrams

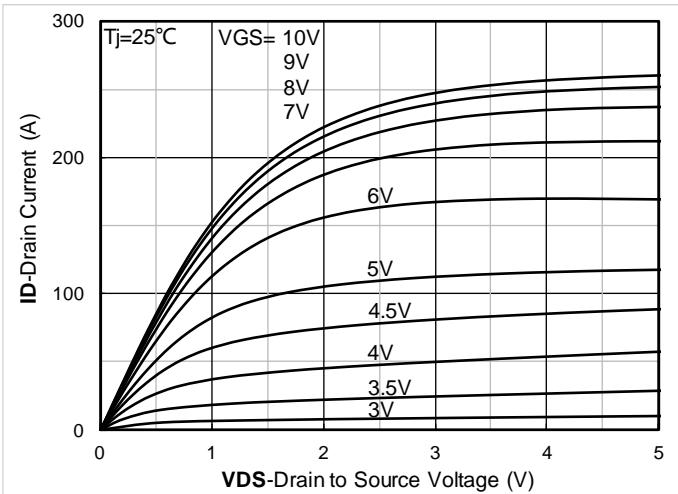


Figure 1. Output Characteristics

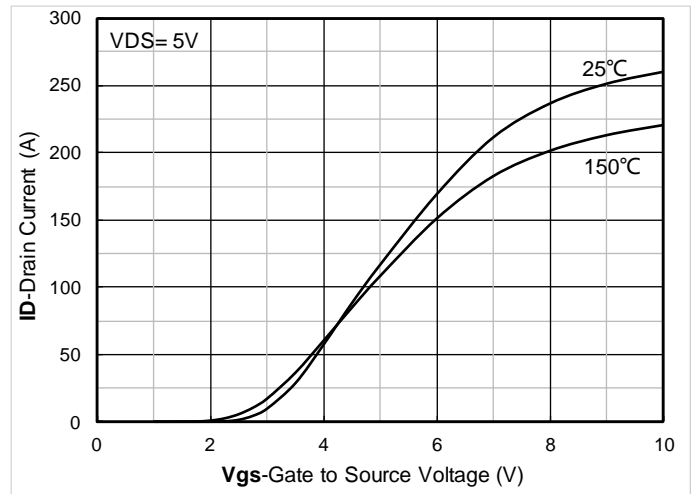


Figure 2. Transfer Characteristics

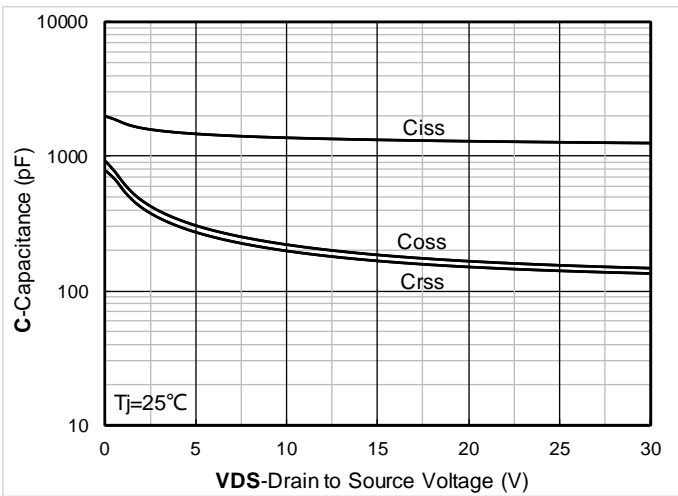


Figure 3. Capacitance Characteristics

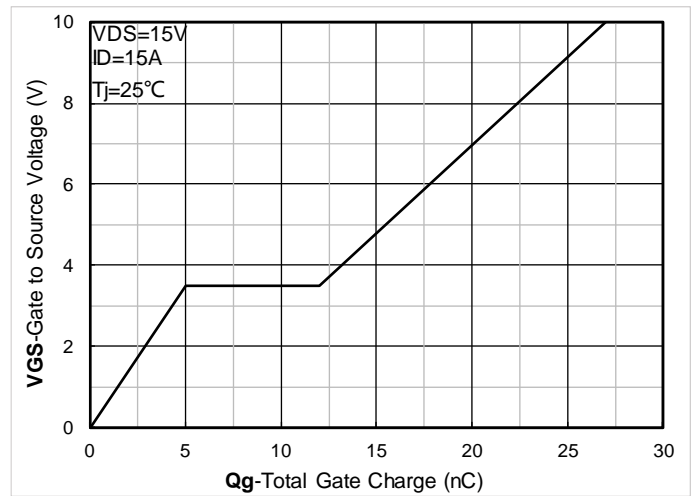


Figure 4. Gate Charge

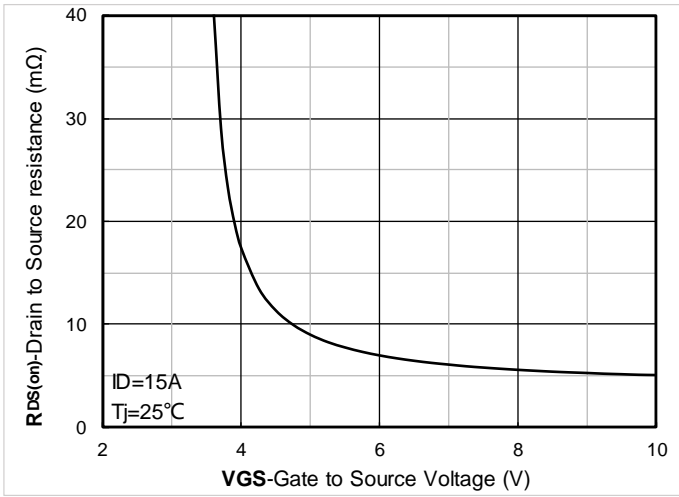


Figure 5. On-Resistance vs Gate to Source Voltage

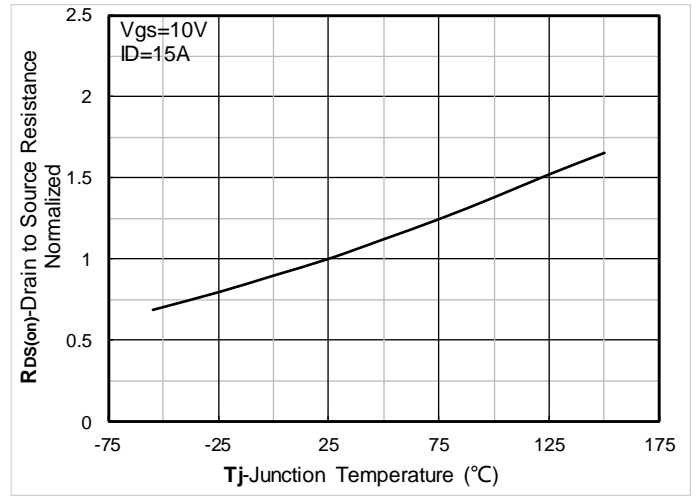


Figure 6. Normalized On-Resistance

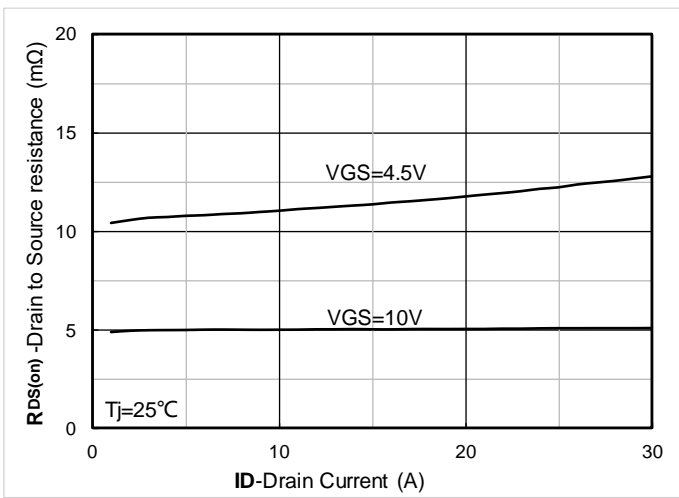


Figure 7. RDS(on) VS Drain Current

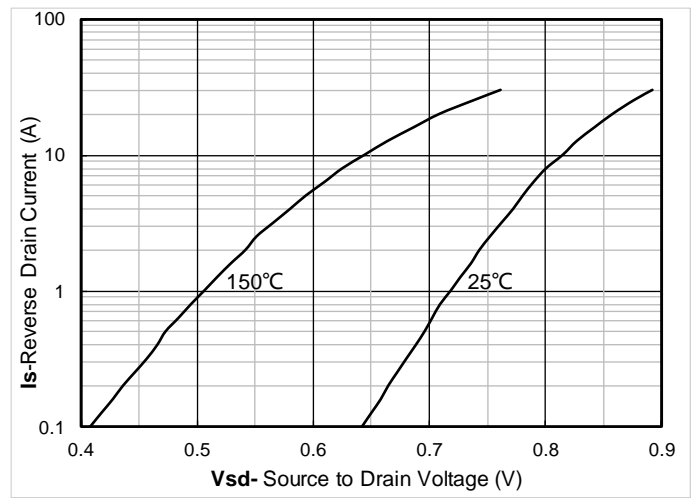


Figure 8. Forward characteristics of reverse diode

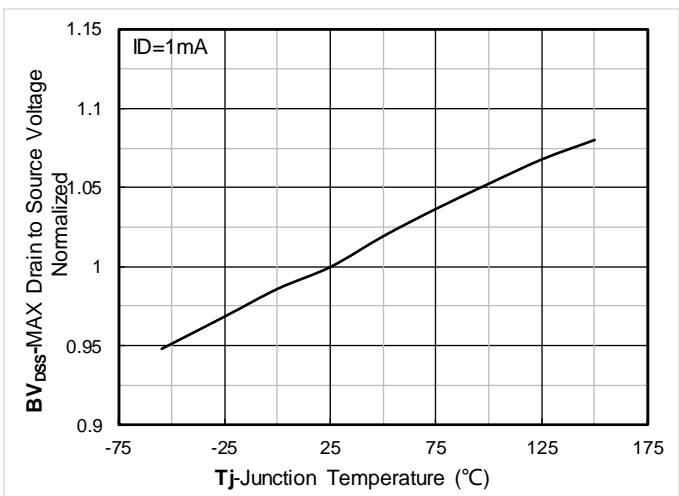


Figure 9. Normalized breakdown voltage

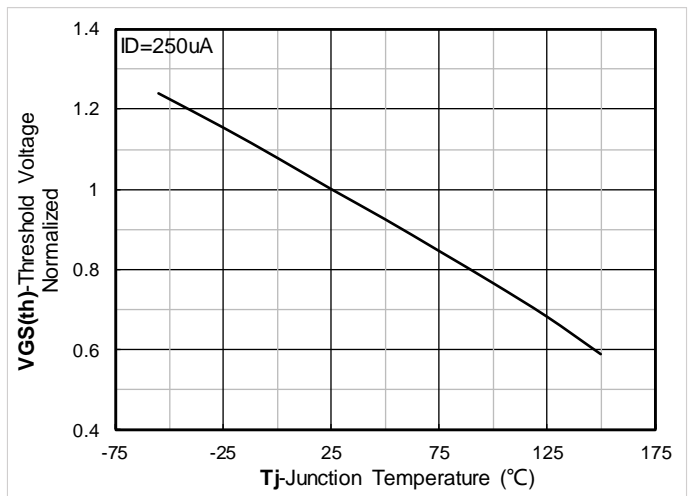


Figure 10. Normalized Threshold voltage



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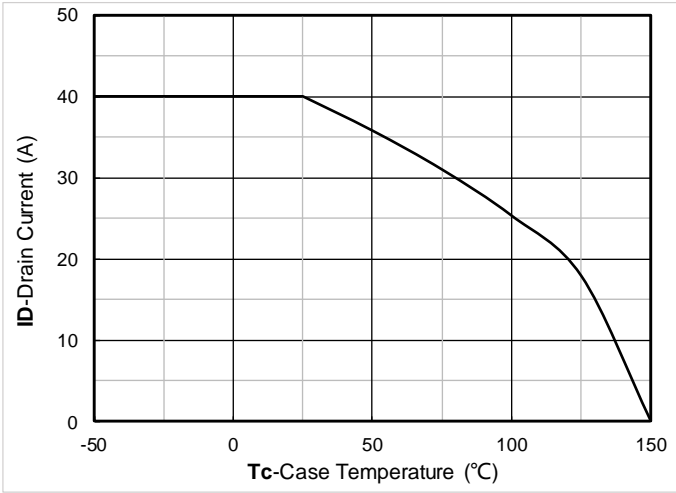


Figure 11. Current dissipation

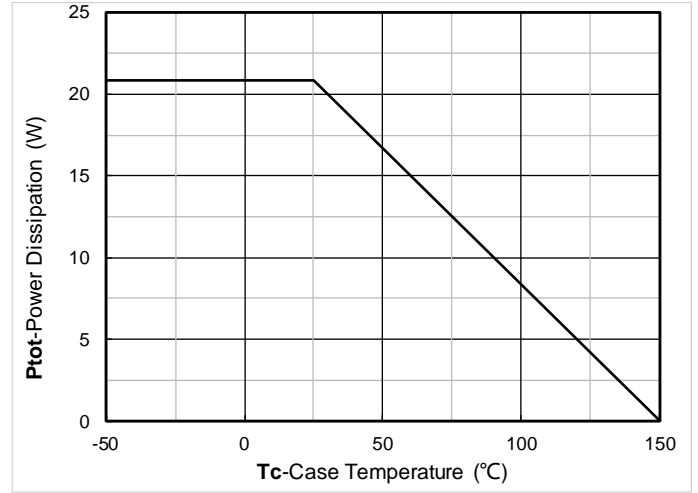


Figure 12. Power dissipation

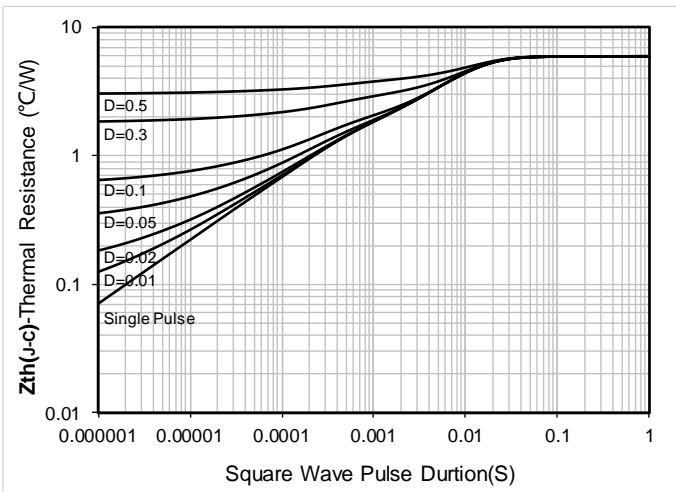


Figure 13. Maximum Transient Thermal Impedance

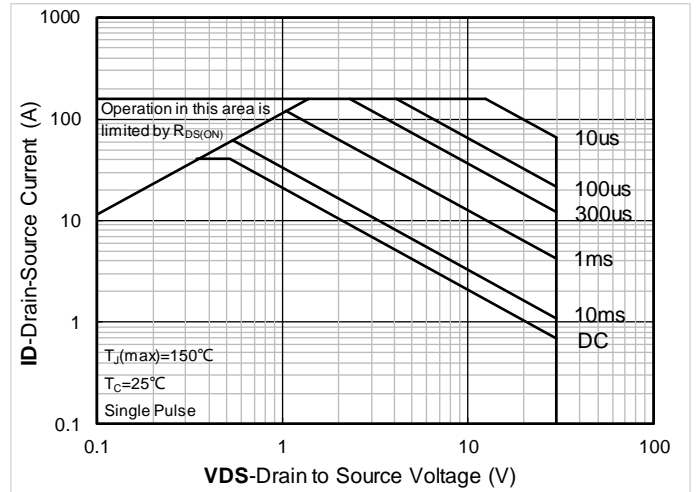
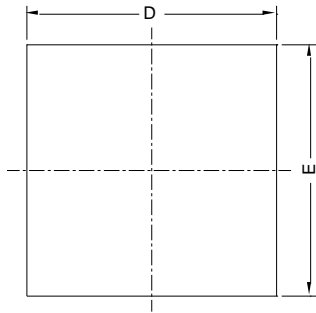


Figure 14. Safe Operation Area

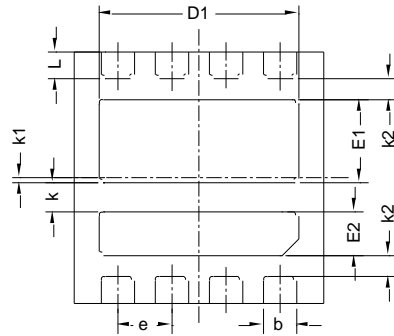


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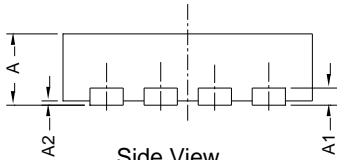
DFN3030-8L Package information



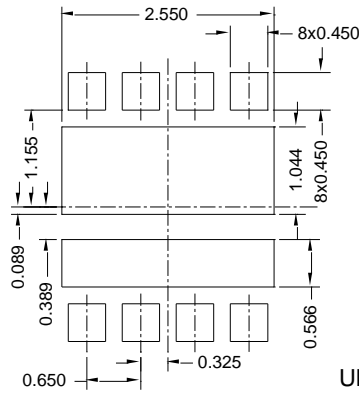
Top View
正面视图



Bottom View
背面视图



Side View
侧面视图



Suggested Solder Pad Layout
Top View

UNIT:mm

SYMBOL	MILLIMETER		
	MIN	NOM	MAX
D	2.90	3.00	3.10
E	2.90	3.00	3.10
A	0.70	0.80	0.90
A1	0.20 BSC		
A2			0.10
D1	2.30	2.40	2.50
E1	0.89	0.99	1.09
E2	0.42	0.52	0.62
L	0.22	0.32	0.42
k	0.35 BSC		
k1	0.06 BSC		
k2	0.25 BSC		
b	0.30	0.40	0.50
e	0.65 BSC		

Note:

1. Controlling dimension: in millimeters.
2. General tolerance: ± 0.10 mm.
3. The pad layout is for reference purposes only.



YJQD3622A

Disclaimer

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